



Click [here](#) for the 3D model.

Dimensions

Chip Size	0805
L	2.01mm +0.3/-0.25mm (0.079 in +0.012/-0.01 in)
W	1.27mm +0.3/-0.25mm (0.05 in +0.012/-0.01 in)
T	1.57mm MAX (0.062 in MAX)
B	0.51mm +/-0.25mm (0.02 in +/-0.01 in)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	100

General Information

Series	SMD MIL BP PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Gold
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.01 uF
Capacitance Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)